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CUSTOMER · CNO003

SAMPLE CODE · SMA480272T016-ZHC

MASS PRODUCTION CODE . HMA480272T016-ZHC

SAMPLE VERSION . 01

SPECIFICATIONS EDITION . 003

DRAWING NO. (Ver.) : LMD- HMA480272T016-ZHC(Ver.002)

PACKAGING NO. (Ver.) : PKG- HMA480272T016-ZHC(Ver.001)

# **Customer Approved**

Date:

Approved	Checked	Designer
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2022.01.11 TW RD APR

- Preliminary specification for design input
- Specification for sample approval

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# **History of Version**

Date (mm / dd / yyyy)	Ver.	Edi.	Description	Page	Design by
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		X			
	X				



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### 1. SPECIFICATIONS

#### 1.1 Features

### **Hardware**

CPU	RISC Processor	STM32H750 480 MHz, ARM Cortex-M7		
	RAM	16MB SDRAM		
	Flash	32MB QSPI FLASH		
	Πασπ	8GB eMMC		
	External Storage	1 x Micro SD (max. 32G)		
	Resolution	480 *3 (RGB) * 272 Dots		
Display	Viewing Direction	Full Viewing Angle		
	Interface	Parallel RGB 24 bits		
	USB	1 x USB2.0 Device		
I/O	Serial	1 x UART, 1 x SPI, 1 x I2C, 1 x CAN		
	RMII	1 x Ethernet		
Power Input	DC	5V		

### Note:

- 1. Support Micro USB Power Supply.
- 2. Support USB Device Full Speed.
- 3. Support CAN Bus (Compatible with ISO11898-2).
- 4. Support Ethernet (10BASE-T / 100BASE-T).
- 5. Support RTC.



# **Mechanical Specifications**

Item	Standard Value	Unit
Outline Dimension	113.2(W) x 73.2(L) x 13.5(H) MAX	mm
Active Area	95.04 (W) * 53.856 (L)	mm

# 1.3 Absolute Maximum Ratings

 $Ta = 25^{\circ}C$ 

Item	Symbol	Condition	Min.	Max.	Unit
Power Supply	VIN	_	4.5	6.0	V
Operating Temperature	Тор		-20	70	$^{\circ}$
Storage Temperature	Tst		-30	80	S
Humidity	HD	Ta=60 °C	10	90	%RH

## **DC Electrical Characteristics**

Ta = 25°C

Item	Sym bol	Condition	Min.	Тур.	Max.	Unit
Power Supply Voltage	VIN	-	4.5	5	5.5	V
Power Supply Voltage of RTC	VBAT	-	2.0		3.6	V
Power Supply Current	IIN	VIN = 5V	-	510	-	mA
Power Consumption of System	PIN	VIN = 5V	-	2.55	-	W
High-Level voltage of digital input	Vін	-	2.3	-	-	V
Low-Level voltage of digital input	VIL	-	-	-	0.9	V
High level voltage of digital output	Vон	-	2.4	-	-	V
Low level voltage of digital output	Vol	-	-	-	0.4	٧



# 1.5 Optical Characteristics

VDD=3.3V, Ta=25 ℃

	1				•	00-0.0	<u>, , , , , , , , , , , , , , , , , , , </u>	
Item	Symbol		Condition	Min.	Тур.	Max.	unit	
Response time	Tr	+Tf	Ta = 25 °C θX, θY = 0°	-	38	57	ms	Note 2
	Тор	θΥ+		-	80	-		
Viewing angle	Bottom	θΥ-	CR≥10	-	80	-	Dog	Note 4
viewing angle	Left	θX-	ON 2 10	1	80	-	Deg.	Note 4
	Right	θΧ+			80	-		
Contrast ratio	Contrast ratio			650	800	-		Note 3
	\\/bito	Х		0.24	0.29	0.34		
	White	Υ	T. 25.00	0.29	0.34	0.39		
	Red	Х		0.55	0.60	0.65		
Color of CIE	neu	Υ	Ta = 25 ℃ θX , θY = 0°	0.30	0.35	0.40		Note1
Coordinate ( With B/L )	Green	Χ	0,7,01 = 0	0.30	0.35	0.40	-	Note
, ,	Green	Υ		0.54	0.59	0.64		
	Blue	X		0.11	0.16	0.21		
	blue	Y		0.09	0.14	0.19		
Average Brightness Pattern=white display (With LCD)*1	IF		PWM="High" (Duty=100%)	650	800	-	cd/m²	Note1
Uniformity (With LCD )*2	Δ	∆B	PWM="High" (Duty=100%)	70	_	-	%	Note1



#### Note 1:

\*1: △B=B(min) / B(max) \* 100%

\*2: Measurement Condition for Optical Characteristics:

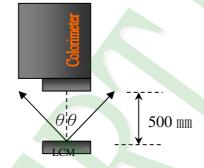
a: Environment: 25°C±5°C / 60±20%R.H, no wind, dark room below 10 Lux at typical lamp current and typical operating frequency

b: Measurement Distance:  $500 \pm 50$  mm,  $(\theta = 0^{\circ})$ 

c: Equipment: TOPCON BM-7 fast, (field 1°), after 10 minutes operation

d: The uncertainty of the C.I.E coordinate measurement ±0.01, Average Brightness ± 4%





Colorimeter=BM-7 fast

To be measured at the center area of panel with a viewing cone of 1° by Topcon luminance meter BM-7, after 10 minutes operation (module)

#### Note 2: Definition of response time:

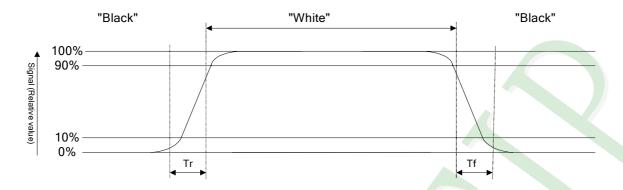
The output signals of photo detector are measured when the input signals are changed from "black" to "white" (falling time) and from "white" to "black" (rising time), respectively. The response time is defined as the time interval between the 10% and 90% of Amplitudes. Refer to figure as below:

# Normally White





### Normally Black



### Note 3: Definition of contrast ratio:

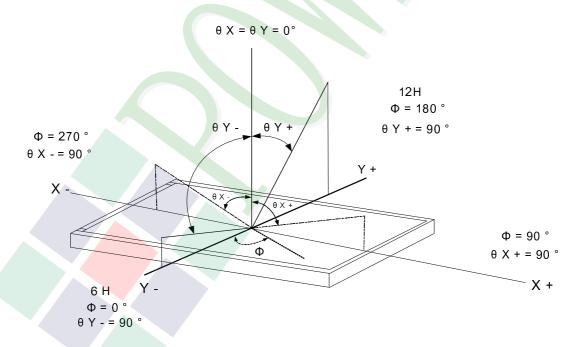
Contrast ratio is calculated with the following formula

Contrast ratio (CR) = Photo detector output when LCD is at "White" state

Photo detector output when LCD is at "Black" state

#### Note 4: Definition of viewing angle:

Refer to figure as below:





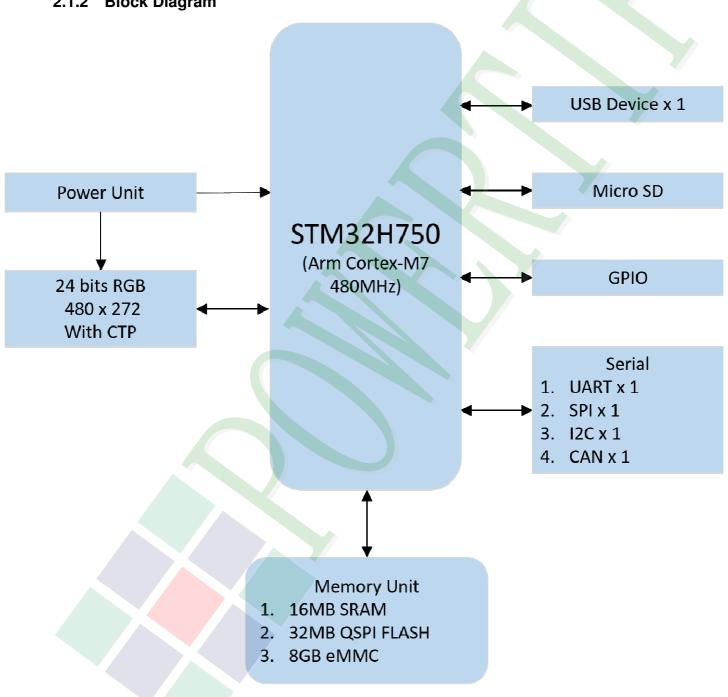
## 2. MODULE STRUCTURE

## 2.1 Counter Drawing

### 2.1.1 Mechanical Diagram

\* See Appendix

### 2.1.2 Block Diagram





## 2.2 Interface Pin Description

## JT1 --- JTAG (Wafer Pitch1.25mm 6pin)

Pin No.	Symbol	Туре	DESCRIPTION
1	PA15	Ю	General Purpose I/O, Port A [15].
2	PA8	Ю	General Purpose I/O, Port A [8].
3	RESETINn	I	JTAG test reset.
4	JTMS/SWDIO	I/O	JTAG test mode select / Serial wire data in/out.
5	JTCK/SWCLK	I	JTAG test clock / Serial wire clock.
6	GND	Р	Ground.

# J3 --- CAN Bus (Wafer Pitch1.25mm 2pin)

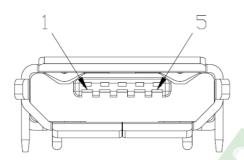
Pin No.	Symbol	Туре	DESCRIPTION
1	CAN H	DS	High Level CAN Bus Line.
2	CAN L	DS	Low Level CAN Bus Line.

# J4 --- USB 2.0 Device MICRO USB

Pin No.	Symbol	Туре	DESCRIPTION
1	VBUS5V	Р	+5.0V
2	D-	DS	Data – (Data M)
3	D+	DS	Data + (Data P)
4	ID	-	Not Used.



Pin No.	Symbol	Туре	DESCRIPTION
5	GND	Р	Ground



## J8 --- RTC (Wafer Pitch1.25mm 2pin)

Pin No.	Symbol	Туре	DESCRIPTION
1	VBAT	Р	Power Supply for RTC.
2	GND	Р	Ground.

# J6 --- Ethernet (Wafer Pitch1.25mm 10pin)

Pin No.	Symbol	Туре	DESCRIPTION			
1	GND	Р	Ground.			
2	GND	P	Ground.			
3	LED_ACK	0	ink Speed LED Indication. (See Note 1)			
4	RXD-	DS	Receive Negative.			
5	RXD+	DS	Receive Positive.			
6	TXD-	DS	Transmit Negative.			
7	TXD+	DS	Transmit Positive.			
8	LED_LINK	0	Link Activity LED Indication. (See Note 2)			
9	GND	Р	Ground.			
10	VDD3V3	Р	Power Supply (+3.3V).			

Note 1: This pin is driven active when the operating speed is 100Mbps. It is inactive when the operating speed is 10Mbps or during line isolation.

Note 2: This pin is driven active when a valid link is detected and blinks when activity is detected.



# J10 --- P05D00071-01 Interface Reserved (Pitch 0.5mm 30pin Double contact)

Pin No.	Symbol	Туре	DESCRIPTION			
1	GND	Р	Ground.			
2	PG3	Ю	General Purpose I/O, Port G [3].			
3	PB2	Ю	General Purpose I/O, Port B [2].			
4	NC	-	Not Used.			
5	GND	Р	Ground.			
6	I2C_CLK	Ю	I2C2 CLK, Function Reserved.			
7	GND	Р	Ground.			
8	I2C_DAT	Ю	I2C2 DAT, Function Reserved.			
9	GND	Р	Ground.			
10	SPI_CLK	Ю	SPI1 CLK, Function Reserved.			
11	GND	Р	Ground.			
12	SPI_MISO	Ю	SPI1 MISO, Function Reserved.			
13	SPI_MOSI	Ю	SPI1 MOSI, Function Reserved.			
14	GND	Р	Ground.			
15	SPI_CS0	Ю	SPI1 CS0, Function Reserved.			
16	GND	Р	Ground.			
17	PH6	Ю	General Purpose I/O, Port H [6].			
18	PH7	Ю	General Purpose I/O, Port H [7].			
19	PH5	Ю	General Purpose I/O, Port H [5].			
20	PB1	Ю	General Purpose I/O, Port B [1].			
21	GND	Р	Ground.			
22	RESETINn	1	System Reset, Active Low.			
23	UART_TXD	Ю	USART2 TX, Function Reserved.			
24	UART_RXD	Ю	USART2 RX, Function Reserved.			
25	GND	P	Ground.			
26	VIN	Р	Power Supply (+5.0V).			
27	VIN	Р	Power Supply (+5.0V).			
28	UART_RTS	10	USART2 RTS, Function Reserved.			
29	UART_CTS	10	USART2 CTS, Function Reserved.			
30	GND	Р	Ground.			



# J13 --- Power Input (Wafer Pitch1.25mm 4pin)

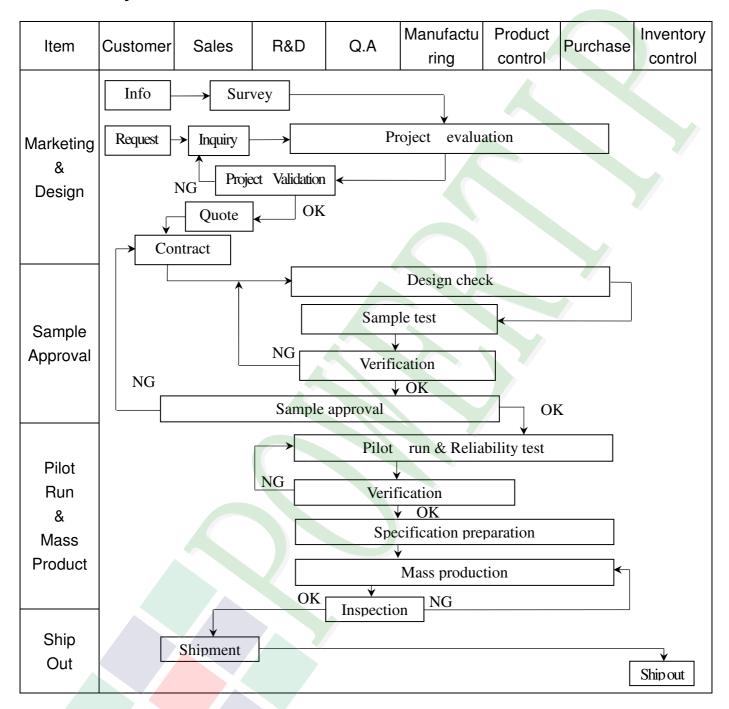
Pin No.	Symbol	Туре	DESCRIPTION			
1	VBUS5V	Р	+5.0V			
2	VBUS5V	Р	+5.0V			
3	GND	Р	Ground			
4	GND	Р	Ground			



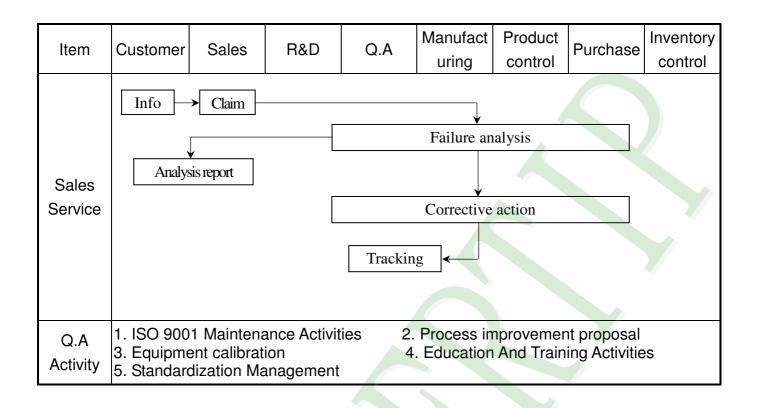


## 3. QUALITY ASSURANCE SYSTEM

## 3.1 Quality Assurance Flow Chart









# 4. RELIABILITY TEST

4.1 Reliability Test Condition

NO.	TEST ITEM	TEST CONDITION				
1	High Temperature Storage Test	Keep in +80 ±2℃ 96 hrs Surrounding temperature, then storage at normal condition 4hrs.				
2	Low Temperature Storage Test	Keep in −30 ±2°C 96 hrs Surrounding temperature, then storage at normal condition 4hrs.				
3	High Temperature / High Humidity Storage Test	Keep in +60℃ / 90% R.H duration for 96 hrs Surrounding temperature, then storage at normal condition 4hrs. (Excluding the polarizer)				
4	Temperature Cycling Storage Test	$-30 \degree C \rightarrow +25 \degree C \rightarrow +80 \degree C \rightarrow +25 \degree C$ $(30 \text{mins})  (5 \text{mins})  (5 \text{mins})$ $ \hline 10 \text{ Cycle}$ Surrounding temperature, then storage at normal condition 4hrs.}				
5	Vibration Test (Packaged)	<ol> <li>Sine wave 10~55 Hz frequency (1 min)</li> <li>The amplitude of vibration :1.5 mm</li> <li>Each direction (X \ Y \ Z) duration for 2 Hrs</li> </ol>				
6	Drop Test (Packaged)	Packing Weight (Kg)         Drop Height (cm)           0 ~ 45. 4         122           45. 4 ~ 90. 8         76           90. 8 ~ 454         61           Over 454         46   Drop direction : ※1 corner / 3 edges / 6 sides each 1 times				



#### 5. PRECAUTION RELATING PRODUCT HANDLING

#### **5.1 SAFETY**

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes, please wash it off immediately by using soap and water.

#### **5.2 HANDLING**

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module, be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So, please handle it very carefully, do not touch, push or rub the exposed polarizing with anything harder than an HB pencil lead (glass, tweezers, etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands, this will stain the display area.
- 5.2.7 Do not use ketonic solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is  $320 \pm 10^{\circ}$ C and  $3 \sim 5$  sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM.
- 5.2.10 Caution! (LCM products with Capacitive Touch Panel)
  Strong EMI-sources such as switch-mode power supplies (SPS) can lead to touch malfunction (e.g., ghost-touches). Therefore, the touch needs to be thoroughly tested inside the target application.
- 5.2.11 CAUTION: Continuously displaying same static image will result in high possibility of image sticking/image burn-in effect due to TFT panel characteristic.
- 5.2.12 Double-sided tape designed to be attached with the customer's mechanical device, please follow up the rules and regulations published by the original manufacturer of double-side tape for the attachment operation.

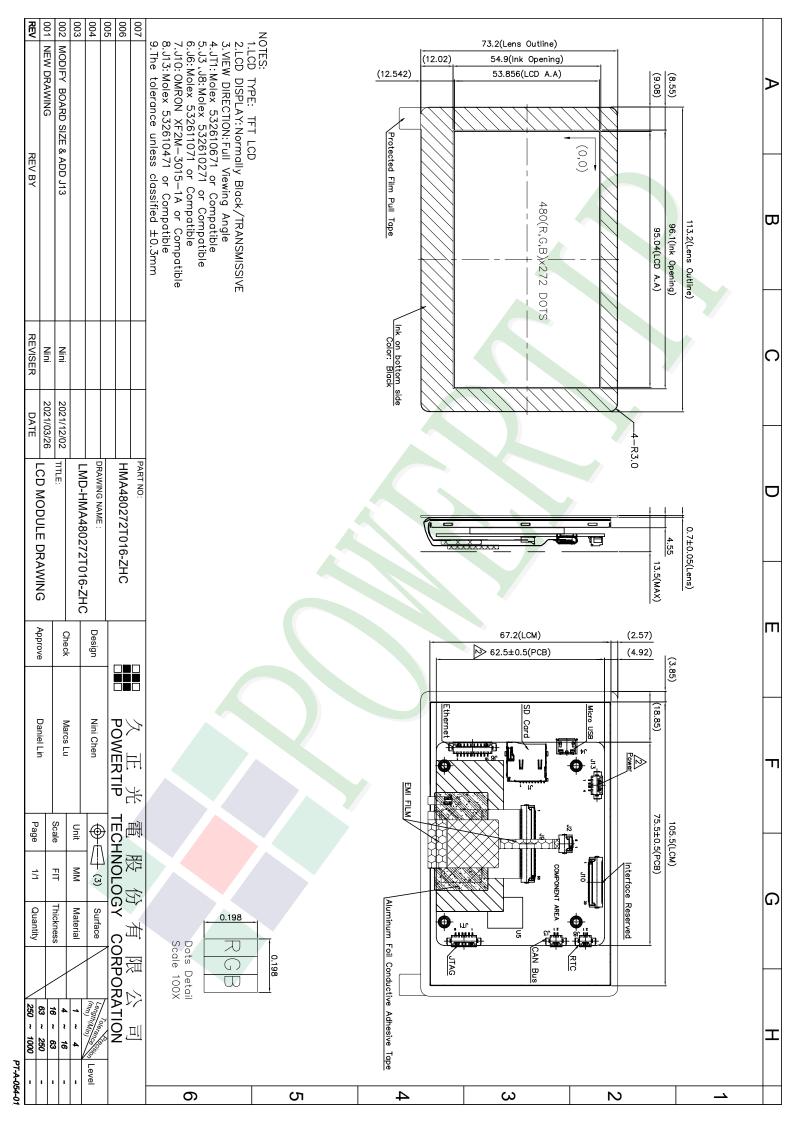
#### **5.3 STORAGE**

- 5.3.1 Store the panel or module in a dark place where the temperature is  $25^{\circ}$ C  $\pm 5^{\circ}$ C and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush, shake, or jolt the module.

#### **5.4 TERMS OF WARRANTY**

- 5.4.1 Applicable warrant period

  The period is within thirteen months since the date of shipping out under normal using and storage conditions.
- 5.4.2 Unaccepted responsibility
  - This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.



Ver.001				Approve	Check	Contact	
Documents NO. PKG-HMA480272T016-ZHC LCM 包裝規格書 LCM Packaging Specifications			Marcs	Bright	Nini		
1.有		: (per carton)					
No.	Item	Model	Dimensions (mm)	1Pcs Weight	Quantity	Total Weight	
1	成品 (Product)	HMA480272T016-ZHC	113.2 X 73.2	0.085	12	1.02	
2	紙內襯 (1)Lined with paper	BX0000000132	347 X 262	0.07	12	0.84	
3	抗靜電袋(2)Antistatic Bag	BAG150120ARABA	120 X 150	0.002	12	0.024	
4	内盒(3)Product Box	BX0000000131	258 X 175 X 58	0.11	12	1.32	
5	内盒(4)Product Box	BX36627063ABBA	383 X 270 X 66	0.2	6	1.2	
6	保利龍板(5)Polylon board	OTPLB00PL08ABA	550 X 393 X 20	0.0284	2	0.0568	
7	外紙箱(6)Carton	BX57041027CCBA	570 X 410 X 265	1.4208	1	1.4208	
8							
9							
10							
11							
12							
3.單 (1)L (2)Te	2.一整箱總重量 (Total LCD Weight in carton ): 5.88 Kg±10% 3.單箱數量規格表 (Packaging Specifications and Quantity):  (1)LCM quantity per small box: no per lined with paper 1 x no of small box 1 = 1  (2)Total LCM quantity in big box: quantity per small box 1 x no of big boxes 2 = 2  (3)Total LCM quantity in carton: quantity per big box 2 x no of cartons 6 = 12						
(1)紙內襯 Lined with paper 成品 Product Box  (2)抗靜電袋 Antistatic Bag  (4)內盒 Product Box  (6)外紙箱 Carton						<b>→</b>	
		特記事項(	REMARK)				